



NEWS RELEASE
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SEC Intros Back Lap Tape Remover

Moorpark, Ca. - Semiconductor Equipment Corp. has introduced a back lap tape remover to compliment it's Model 3250 Back Lap Tape Applicator giving it the ability to double as both an applicator and remover. The tape applicator applies back lapping tape to the top side of a wafer to offer protection during the backside grinding process. Once the wafer is thinned the tape is gently peeled off the wafer while being held by a slip on vacuum chuck that drops onto the tape applicator. The new system works for all size wafers up to 200 mm.

Semiconductor Equipment Corporation is recognized as the leading manufacturer and distributor of standard and customized die handling equipment and semiconductor dicing tape. Since 1975, SEC has installed thousands of production units worldwide for work in packaging and assembly operations including edge emitting lasers, flipchip, surface mount, and hi-reliability devices such as ball grid arrays, quad flat packs, and multi-chip modules.